



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Teck Kheng Lee

Serial No.: 10/829,603

Filed: April 22, 2004

For: METHODS FOR ASSEMBLY AND
PACKAGING OF FLIP CHIP
CONFIGURED DICE WITH INTERPOSER

Confirmation No.: 6862

Examiner: Unknown

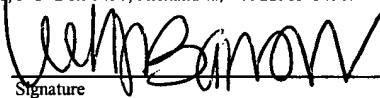
Group Art Unit: 2823

Attorney Docket No.: 2269-4974.2US
(00-0693.02/US)

CERTIFICATE OF MAILING

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 or PTO/SB/08 be considered by the Examiner and made of record. Copies of U.S. patents are not being submitted pursuant to M.P.E.P. 609 III A(2). Copies of foreign patent documents and non-patent literature are enclosed pursuant to 37 C.F.R. § 1.98(a)(2).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicant herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

U.S. Patent Documents

<u>U.S. Patent No.</u>	<u>Publication Date</u>	<u>Patentee</u>
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US - 4,074,342	02/1978	Honn et al.
US - 4,818,728	04/1989	Rai et al.
US - 5,148,265	09/1992	Khandros
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US - 6,177,723	01/2001	Eng et al.
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US - 6,756,251	06/2004	Lee
US - 6,791,195	09/2004	Urushima
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Foreign Patent Documents

<u>Document No.</u>	<u>Publication Date</u>	<u>Patentee</u>
EP 684644	11/1995	Kata et al.
EP 1009027	06/2000	Okuno
KR 2001054744	07/2001	Choi et al. (English Abstract)

Other Documents

AL-SARAWI et al., A A review of 3-D packaging technology,@ Components, Packaging, and Manufacturing Technology, Part B: IEEE Transactions on Advanced Packaging, Vol 21, Issue 1, Feb. 1998, pp. 2-14.

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CLOT et al., A Flip-Chip on Flex for 3D Packaging,@ 1999. 24th IEEE/CPMT, 18-19 Oct. 1999, pp. 36-41.

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KLOESER et al., A Fine Pitch Stencil Printing of Sn/Pb and Lead Free Solders for Flip Chip Technology,@ IEEE Transactions of CPMT - Part C, vol. 21, No. 1, 1998, pp. 41-49.

LEE et al., A Enhancement of Moisture Sensitivity Performance of a FBGA,@ Proceedings of International Symposium on Electronic Materials & Packaging, 2000, pp. 470-475.

Other Documents

LI et al., A Stencil Printing Process Development for Flip Chip Interconnect, @ IEEE Transactions Part C: Electronics Packaging Manufacturing, Vol. 23, Issue 3, (July 2000), pp. 165-170.

LYONS et al., "A New Approach to Using Anisotropically Conductive Adhesives for Flip-Chip Assembly, Part A, " *IEEE Transactions on Components, Packaging, and Manufacturing Technology*, Vol. 19, Issue 1, March 1996, pp. 5-11.

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TEUTSCH et al, "Wafer Level CSP using Low Cost Electroless Redistribution Layer," *Electronic Components and Technology Conference*, 2000. 2000 Proceedings. 50th, 21-24 May 2000, pp. Pages: 107-113.

"The 2003 International Technology Roadmap for Semiconductor: Assembly and Packaging."

TSUI et al., "Pad redistribution technology for flip chip applications," *Electronic Components and Technology Conference*, 1998. 48th IEEE, 25-28 May 1998, pp. 1098-1102.

XIAO et al., "Reliability study and failure analysis of fine pitch solder-bumped flip chip on low-cost flexible substrate without using stiffener," IEEE, 2002. Proceedings 52nd, 28-31 May 2002, pp. 112-118.

Applicant offers to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

This Supplemental Information Disclosure Statement is filed before the mailing date of a first Office Action on the merits.

Respectfully submitted,



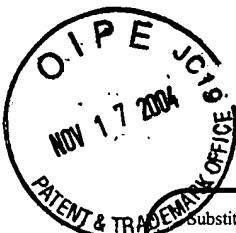
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Date: November 15, 2004

TNB/lmh:ljb

Enclosures: Form PTO-1449 or PTO/SB/08
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Complete if Known	
Application Number	10/829,603
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First Named Inventor	Teck Kheng Lee
Group Art Unit	2823
Examiner Name	Unknown

Attorney Docket Number 2269-4974.2US (00-0693.02/US)

U.S. PATENT DOCUMENTS

Examiner Initials *	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ² (if known)			
		US-3,239,496	03/1966	Jursich	
		US- 4,074,342	02/1978	Honn et al.	
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		Country Code ³ - Number ⁴ - Kind Code ⁵ (if known)				
		EP 684644	11/1995	Kata et al.		
		EP 1009027	06/2000	Okuno		
		KR 2001054744	07/2001	Choi et al. (English Abstract)		x

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NON PATENT LITERATURE DOCUMENTS

Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		AL-SARAWI et al., AA review of 3-D packaging technology, @ Components, Packaging, and Manufacturing Technology, Part B: IEEE Transactions on Advanced Packaging, Vol 21, Issue 1, Feb. 1998, pp. 2-14.	
		ANDROS et al., ATBGA Package Technology, @ Components, Packaging, and Manufacturing Technology, Part B: IEEE Transactions on Advanced Packaging, Vol. 17, Issue 4, Nov. 1994, pp. 564-568.	
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